

### UT4101G-AE3-R-VB Datasheet

# P-Channel 20-V (D-S) MOSFET

MOSFET PRODUCT SUMMARY						
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)			
	0.060 at V <sub>GS</sub> = - 10 V	- 4.0				
- 20	0.065 at V <sub>GS</sub> = - 4.5 V	- 3.5	10 nC			
	0.080 at V <sub>GS</sub> = - 2.5 V	- 2.0				

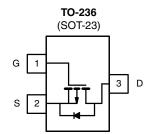
#### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Definition
- Trench Power MOSFET
- 100 % R<sub>g</sub> Tested
- Compliant to RoHS Directive 2002/95/EC



#### **APPLICATIONS**

- · Load Switch
- PA Switch
- DC/DC Converters



Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	$V_{DS}$	- 20	V		
Gate-Source Voltage	V <sub>GS</sub>	± 12			
	T <sub>C</sub> = 25 °C		- 4 <sup>e</sup>		
Continuous Drain Current (T <sub>.1</sub> = 150 °C)	$T_C = 70  ^{\circ}C$	l <sub>D</sub>	-3.2		
Continuous Brain Carroni (1) = 100 °C)	T <sub>A</sub> = 25 °C	טי	- 3 .5 <sup>b, c</sup>		
	T <sub>A</sub> = 70 °C		- 2 .5 <sup>b, c</sup>	Α	
Pulsed Drain Current	I <sub>DM</sub>	- 10			
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C	Is	- 2.1		
Continuous Source-Diam Diode Current	T <sub>A</sub> = 25 °C	'S	- 1.0 <sup>b, c</sup>	i	
	T <sub>C</sub> = 25 °C		2.5		
Maximum Power Dissipation	T <sub>C</sub> = 70 °C	$P_{D}$	1.6	w	
Maximum Fower Dissipation	T <sub>A</sub> = 25 °C	' D	1.25 <sup>b, c</sup>	- vv	
	T <sub>A</sub> = 70 °C		0.8 <sup>b, c</sup>		
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stq</sub>	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient <sup>b, d</sup>	≤ 5 s	$R_{thJA}$	75	100	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	$R_{thJF}$	40	50	C/ VV		

#### Notes:

- a. Based on T<sub>C</sub> = 25 °C.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 5 s.
- d. Maximum under steady state conditions is 166  $^{\circ}\text{C/W}.$
- e. Package limited.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{DS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$	- 20			V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	ş/T <sub>J</sub>		- 13.4		mV/°C
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = - 250 μA		2.9		- mv/·c
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 0.5		- 1.5	V
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$			± 100	nA
Zava Cata Valtaga Dvain Current		$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}$			- 1	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$		- 10 <sup>µ</sup>		- μΑ
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \le -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	- 10			Α
		V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 3 A		0.060		
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 2.5 A		0.065		Ω
		V <sub>GS</sub> = - 2.5 V, I <sub>D</sub> = - 2 A		0.080		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 5 V, I <sub>D</sub> = - 3 A		15		S
Dynamic <sup>b</sup>					l	
Input Capacitance	C <sub>iss</sub>			835		pF
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> = - 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz		180		
Reverse Transfer Capacitance	C <sub>rss</sub>			155		
T. 10 . 0		V <sub>DS</sub> = - 10 V, V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 3.1 A		10		
Total Gate Charge		50 GO 5		6.4		
Gate-Source Charge	$Q_{gs}$	$V_{DS} = -10 \text{ V}, V_{GS} = -2.5 \text{ V}, I_{D} = -3.1 \text{ A}$		1.7		nC
Gate-Drain Charge	$Q_{gd}$	30 3		3.4		
Gate Resistance	$R_{g}$	f = 1 MHz	0.9	4.4	8.8	Ω
Turn-On Delay Time	t <sub>d(on)</sub>			22	33	
Rise Time	t <sub>r</sub>	$V_{DD} = -10 \text{ V, R}_{L} = 2.4 \Omega$		20	30	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D = -3.1 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$		28	42	ns
Fall Time	t <sub>f</sub>			9	18	
<b>Drain-Source Body Diode Characteristic</b>	cs				L	<u>.</u> L
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			- 2.1	_
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				- 1 0	Α
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = - 3.1 A		- 0.8	- 1.2	٧
Body Diode Reverse Recovery Time	t <sub>rr</sub>	-		23	35	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			12	20	nC
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = -3.1 \text{ A, dI/dt} = 100 \text{ A/}\mu\text{s, T}_J = 25 ^{\circ}\text{C}$		15		
Reverse Recovery Rise Time	t <sub>b</sub>	_		8		ns

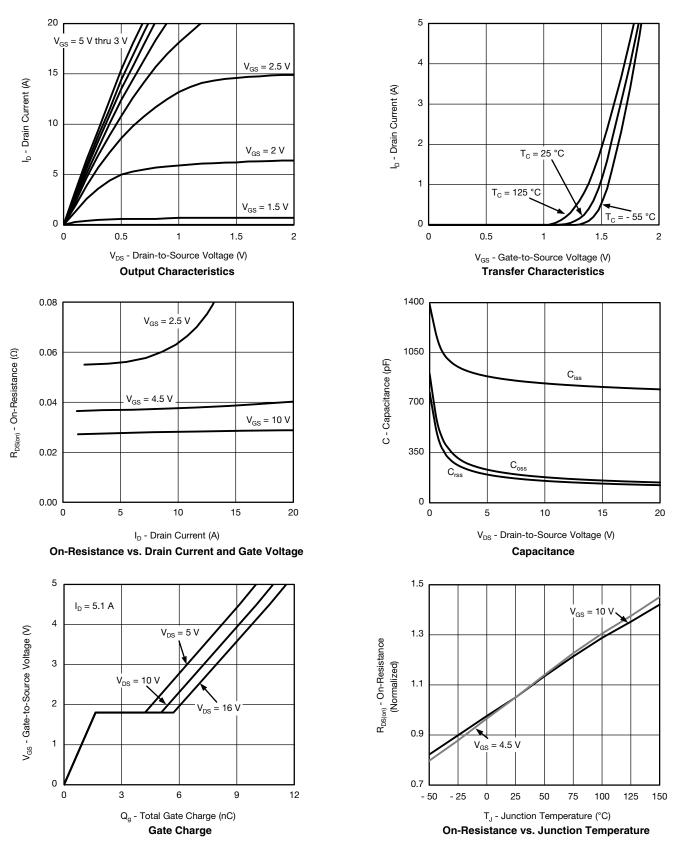
#### Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

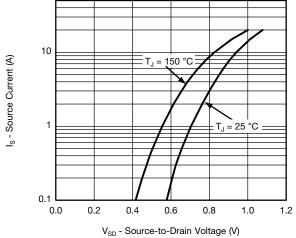
a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.

b. Guaranteed by design, not subject to production testing.

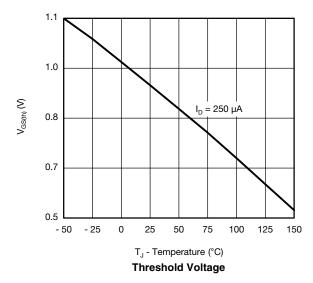


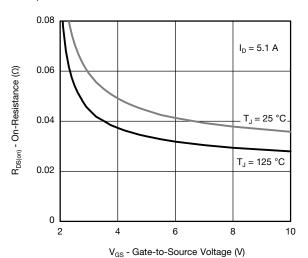




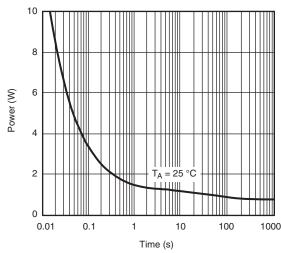


#### Source-Drain Diode Forward Voltage

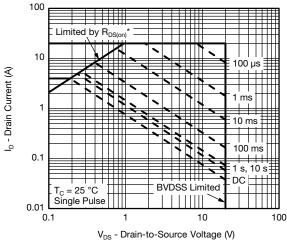




On-Resistance vs. Gate-to-Source Voltage



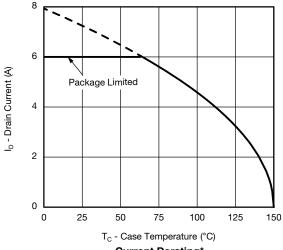
Single Pulse Power



\*  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

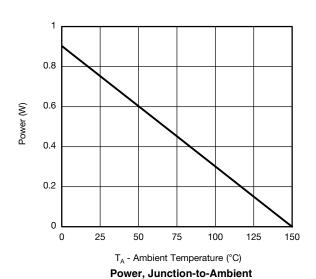
Safe Operating Area





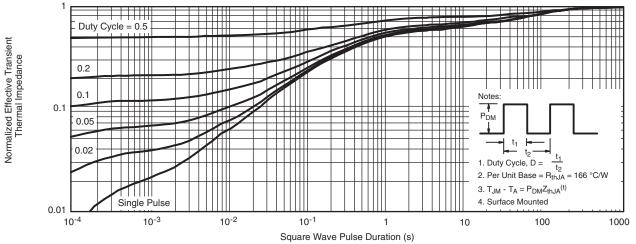




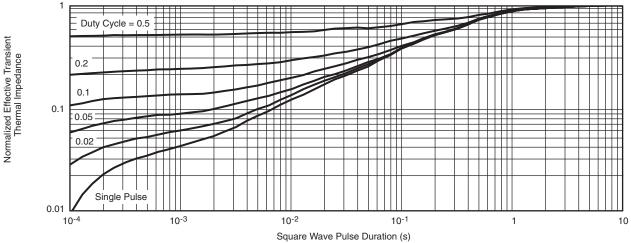


<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





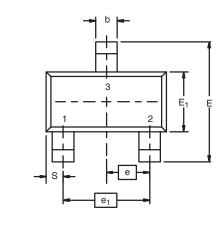
Normalized Thermal Transient Impedance, Junction-to-Ambient

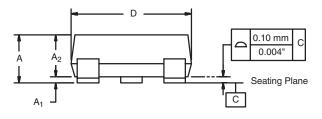


Normalized Thermal Transient Impedance, Junction-to-Foot



## SOT-23 (TO-236): 3-LEAD







Dim	MILLI	METERS	INCHES		
	Min	Max	Min	Max	
Α	0.89	1.12	0.035	0.044	
A <sub>1</sub>	0.01	0.10	0.0004	0.004	
A <sub>2</sub>	0.88	1.02	0.0346	0.040	
b	0.35	0.50	0.014	0.020	
С	0.085	0.18	0.003	0.007	
D	2.80	3.04	0.110	0.120	
E	2.10	2.64	0.083	0.104	
E <sub>1</sub>	1.20	1.40	0.047	0.055	
е	0.9	5 BSC	0.037	4 Ref	
e <sub>1</sub>	1.9	0 BSC	0.074	8 Ref	
L	0.40	0.60	0.016	0.024	
L <sub>1</sub>	0.64 Ref		0.025 Ref		
S	0.50 Ref		0.020 Ref		
q	3°	8°	3°	8°	
FCN: S-03946-Rev K 09-	Jul-01	•			

ECN: S-03946-Rev. K, 09-Jul-01

DWG: 5479



#### **RECOMMENDED MINIMUM PADS FOR SOT-23**



Recommended Minimum Pads Dimensions in Inches/(mm)

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